



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR MSOP

Stress	Sample Size	Device Hr./Cyc	Condition	Total Fails	Fail Percentage
BOND INT	80	90,000	200°C + N2	0	0.00
HAST	1,130	118,500	130°C, 85%RH	0	0.00
Pressure Pot	2,180	214,560	121°, 15 PSIG	0	0.00
Solder DUNK	515	1,545	260°C, 10SEC	0	0.00
Solderability	420	3,480	883 M2003	0	0.00
Temp Cycle	2,685	746,250	-65°C-150°C	0	0.00